

This notice is to inform you of a change that will be made to certain ADI products (see Appendix A) that you may have purchased in the last 2 years. **Any inquiries or requests with this PCN (additional data or samples) must be sent to ADI within 30 days of publication date.** ADI contact information is listed below.

<b>PCN Title:</b>	Change in Die Attach and Mold Compound materials for MAX20091ATM/V+T device at Assembler UTAC THAI LIMITED/Thailand (UTL) - T4877+6C
<b>Publication Date:</b>	28-Sep-2023
<b>Effectivity Date:</b>	31-Dec-2023 (the earliest date that a customer could expect to receive changed material)
<b>Revision Description:</b>	

**Description Of Change:**

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Change in Die Attach and Mold Compound materials for MAX20091ATM/V+T device at Assembler UTAC THAI LIMITED/Thailand

Die Attach: AB8200T

Mold Compound: G770HCD

**Reason For Change:**

This change is to standardize bill of materials at Assembler UTAC THAI LIMITED/Thailand.

AB8600 Die Attach and G700LTD Mold Compound are existing standard materials for many other ADI devices at this site.

- The AECQ-100 Qualification report is attached.
- There are no regulatory compliance changes to the material content of the device.
- There are no changes to the form/fit/function of the device.

**Impact of the change (positive or negative) on fit, form, function & reliability:****Product Identification (this section will describe how to identify the changed material):****Summary of Supporting Information:****Supporting Documents:****ADI Contact Information:**

For questions on this PCN, please send an email to the regional contacts below or contact your local ADI sales representatives.

<b>Americas:</b>	<b>Europe:</b>	<b>Japan:</b>	<b>Korea:</b>	<b>Rest of Asia:</b>
PCN_Americas@analog.com	PCN_Europe@analog.com	PCN_Japan@analog.com	PCN_Korea@analog.com	PCN_ROA@analog.com

**Appendix A - Impacted items, see csv PN listing in PCN Zip file**